

REMARKS

A listing of the claims has not been provided as none of the claims have been amended. Claims 1-3, 6-9, 11, 12, 14, 16-20, 34, 36, 38-42, 46, and 51 are pending. Claims 1-3, 6-9, 11, 12, 14, 16-20, 34, 36, 38-42, 46, and 51 stand rejected. Applicant reserves the right to pursue the original claims and other claims in this application and in other applications.

Claims 1-3, 6-9, 11, 12, 14, 16-20 and 34, 36, 38-42, 46, and 51 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Amagai (U.S. Patent No. 6,232,661) in combination with Forray (U.S. Pub. No. 2002/0062923). The rejection is respectfully traversed and reconsideration is respectfully requested.

The claimed inventions relate to a prepackaged semiconductor device assembly. As such, independent claim 1 recites a prepackaged semiconductor device assembly comprising “a solder mask over a substrate; a die; conductive paths connecting contacts on said die with contacts in said substrate; and an adhesive layer which is only partially cured for adhering said die to said solder mask.”

Independent claim 12 recites a prepackaged semiconductor device assembly comprising “a solder mask on a substrate; a die; electrical contacts on said substrate and said die, each contact on said die being connected to a respective contact on said substrate, said electrical contacts being devoid of contamination caused by outgassing from said solder mask; and an adhesive layer which is only partially cross-linked affixing said die to said solder mask.”

The references, alone or in combination, fail to disclose, teach, or suggest a prepackaged semiconductor device assembly comprising, *inter alia*, “an adhesive layer which is only partially cured *for adhering said die to said solder mask*,” as recited by claim 1. As the Office Action admits (at page 3), Amagai fails “to disclose a partially-cured adhesive layer.” The Office Action cites Forray to allegedly cure the shortcomings of Amagai; the Office Action fails, however, to show where Forray discloses, teaches, or suggests a “an adhesive layer which is only partially cured for adhering said die to said solder mask,” as recited by claim 1.

Indeed, Forray specifically teaches applying an adhesive in an uncured state to a surface of a device, contacting the surface of the device to a surface of a substrate, and curing the

adhesive to form a bond between the two surfaces. *See* Forray at ¶¶ [0008] to [0010]. Nowhere in its description does Forray disclose, teach, or suggest “an adhesive layer which is *only partially cured* for *adhering said die to said solder mask*,” as recited by claim 1.

Accordingly, Applicant respectfully submits that claim 1 is allowable over the references of record.

Claims 2, 3, 6-9, 11, 34, 38, 39, 41, and 42 depend from claim 1, and are allowable for at least the same reasons set forth above with respect to claim 1 and on their own merits.

Accordingly, Applicant respectfully requests that the rejection be withdrawn and the claims allowed.

Claim 12 is also not rendered obvious by the cited references. The references, alone or in combination, fail to disclose, teach, or suggest each and every limitation of claim 12. Specifically, as discussed above with respect to claim 1, the references fail to disclose, teach, or suggest “an adhesive layer which is only partially cross-linked affixing said die to said solder mask,” as recited by claim 12. Accordingly, Applicant respectfully submits that claim 12 is allowable over the references of record.

Claims 14, 16-20, 36, 40, 46, and 51 depend from claim 12, and are allowable for at least the same reasons set forth above with respect to claim 12 and on their own merits.

Accordingly, Applicant respectfully requests that the rejection be withdrawn and the claims allowed.

In view of the above, Applicant believes the pending application is in condition for allowance.

The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 04-1073, under Order No. M4065.0226/P226.

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Respectfully submitted,

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